



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: 1756

Application Number: 10/670,291

Examiner: **Daborah Chacko-Davis**

Filed: September 26, 2003

Confirmation No.: 6427

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR FORMING RESIST PATTERN, AND PROCESS FOR MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: 031181

Customer Number: 38834

AMENDMENT AFTER FINAL REJECTION

Mail Stop AF
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

November 20, 2006

Sir:

This paper is filed in response to the Office Action dated August 22, 2006.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 7 of this paper.